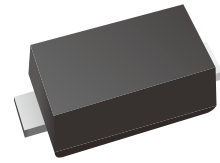


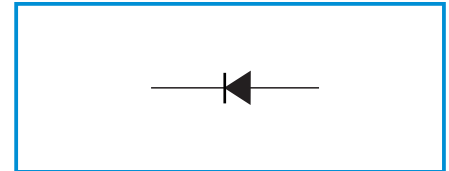
Surface Mount Ultrafast Recovery Rectifier

Features

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place
- High efficiency
- Lead free in comply with EU RoHS 2011/65/EU directives



Functional Diagram



Mechanical Data

- Case: SMAF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 27mg 0.00095oz
- Polarity: Color band denotes cathode end

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	LTU2AF	LTU2BF	LTU2DF	LTU2GF	LTU2JF	LTU2KF	LTU2MF	Units	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V	
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V	
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V	
Maximum Average Forward Rectified Current at $T_c = 125\text{ }^\circ\text{C}$	$I_{F(AV)}$	2							A	
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	50							A	
Maximum Instantaneous Forward Voltage at 2 A	V_F	1.0		1.3		1.65			V	
Maximum DC Reverse Current $T_a = 25\text{ }^\circ\text{C}$ at Rated DC Blocking Voltage $T_a = 125\text{ }^\circ\text{C}$	I_R	5 100							μA	
Maximum Reverse Recovery Time ⁽¹⁾	t_{rr}	50				75				ns
Typical Thermal Resistance ⁽²⁾	$R_{\theta JA}$ $R_{\theta JC}$	65 20							$^\circ\text{C/W}$	
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150							$^\circ\text{C}$	

(1) Measured with $I_F = 0.5\text{ A}$, $I_R = 1\text{ A}$, $I_{rr} = 0.25\text{ A}$.

(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Ratings and characteristics Curves

Fig.1 Forward Current Derating Curve

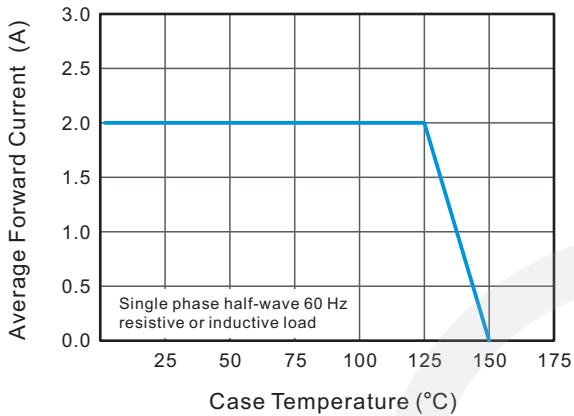


Fig.2 Typical Reverse Characteristics

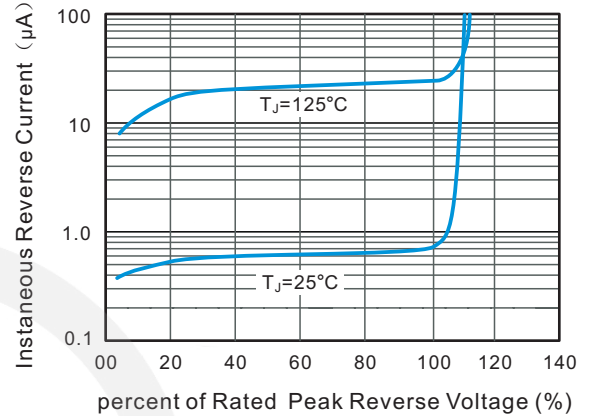


Fig.3 Typical Forward Characteristics

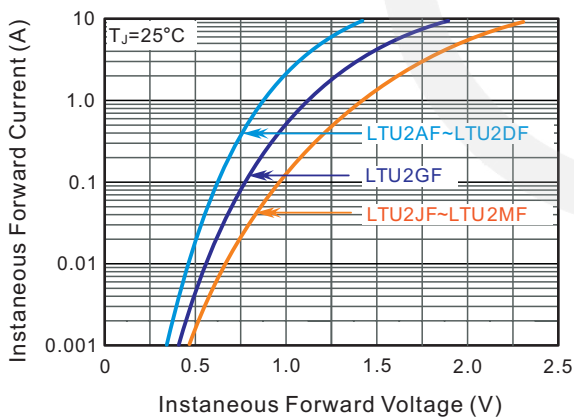
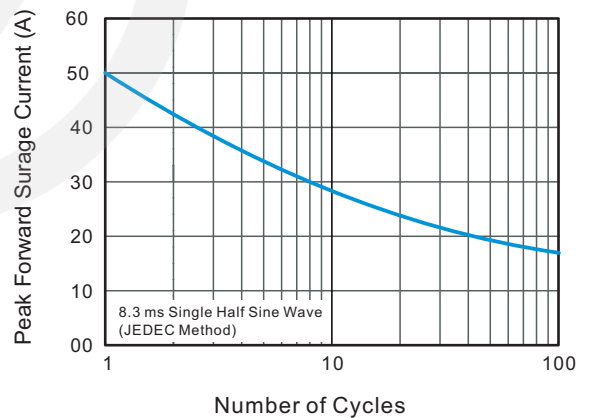
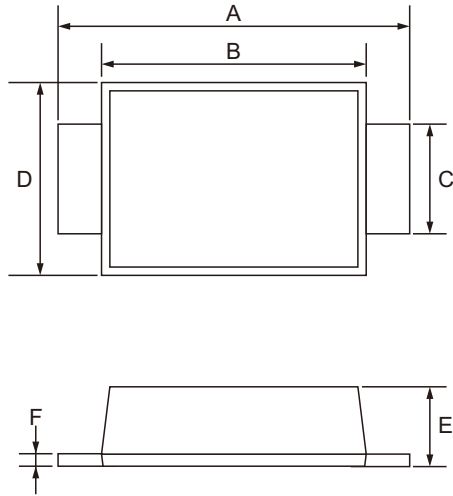


Fig.4 Maximum Non-Repetitive Peak Forward Surge Current



SMAF Package Outline



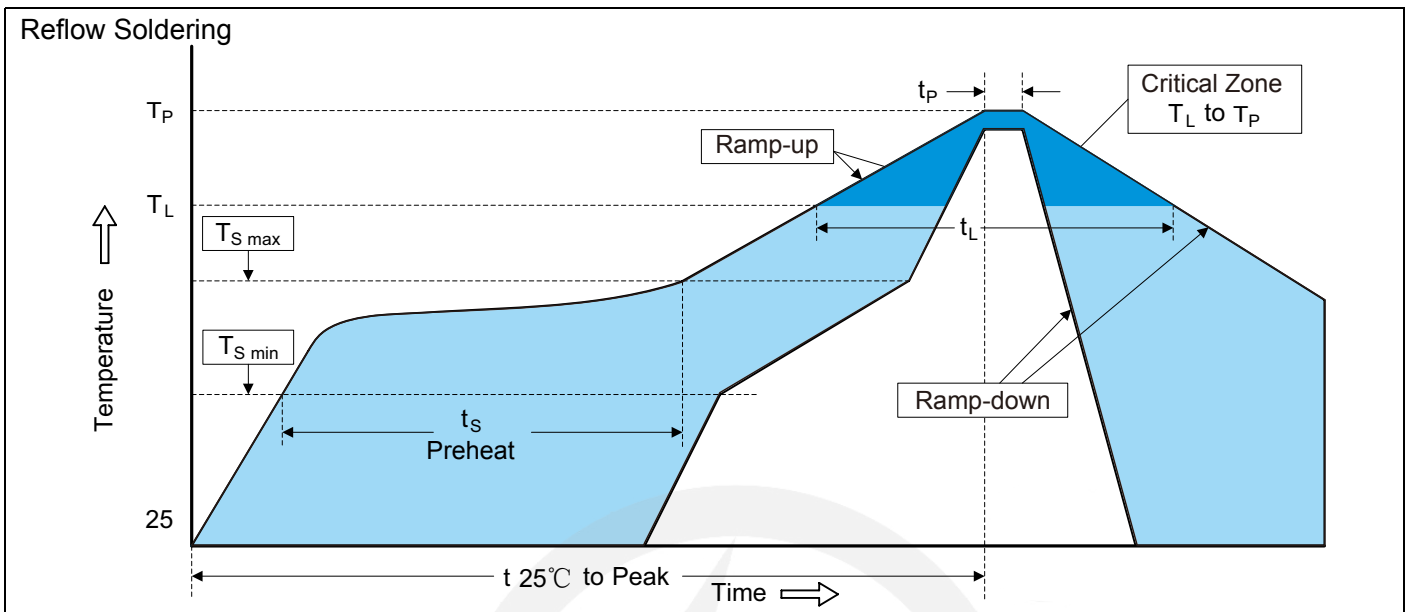
SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	4.40	4.90
B	3.30	3.70
C	1.30	1.60
D	2.40	2.70
E	0.90	1.20
F	0.12	0.20

Marking

Type number	Marking code
LTU2AF	US2A
LTU2BF	US2B
LTU2DF	US2D
LTU2GF	US2G
LTU2JF	US2J
LTU2KF	US2K
LTU2MF	US2M



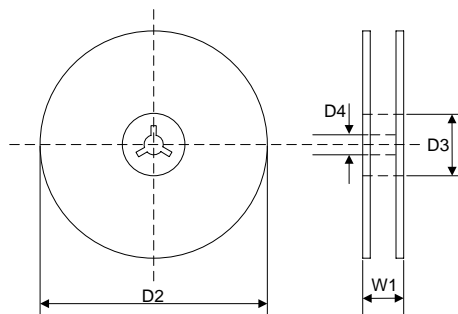
Recommended Soldering Conditions



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T _L to T _P)	3°C/second max.
Preheat	
-Temperature Min (T _{S min})	150°C
-Temperature Max (T _{S max})	200°C
-Time (min to max) (t _S)	60-180 seconds
T _{S max} to T _L	
-Ramp-up Rate	3°C/second max.
Time maintained above:	
-Temperature (T _L)	217°C
-Time (t _L)	60-150 seconds
Peak Temperature (T _P)	260°C
Time within 5°C of actual Peak Temperature (t _P)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

7" Reel



D2 Φ178.0±2.0

D3 Φ50.0Min.

D4 Φ13.0±0.5

W1 16.0±2.0

Quantity: 3000PCS